- Can Be Used as Two 16-Bit Counters or a Single 32-Bit Counter
- 2-V to 5.5-V V_{CC} Operation
- Max t_{pd} of 25 ns at 5 V (RCLK to Y)
- Typical V_{OLP} (Output Ground Bounce)
 <0.7 V at V_{CC} = 5 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot) >4.4 V at V_{CC} = 5 V, T_A = 25°C
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22

 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

description/ordering information

	N OR PW PACKAGE (TOP VIEW)							
CLKA CLKB GAL GAU GBU GBU RCLK RCOA CLKBEN	1 2 3 4 5 6 7 8 9	20 19 18 17 16 15 14 13 12	V _{CC} Y0 Y1 Y2 Y3 Y4 Y5 Y6 Y7					
GND	10	11	CCLR					

The SN74LV8154 is a dual 16-bit binary counter with 3-state output registers, designed for 2-V to 5.5-V V_{CC} operation.

This 16-bit counter (A or B) feeds a 16-bit storage register, and each storage register is further divided into an upper byte and lower byte. The GAL, GAU, GBL, GBU inputs are used to select the byte that needs to be output at Y0–Y7. CLKA is the clock for A counter, and CLKB is the clock for B counter. RCLK is the clock for the A and B storage registers. All three clock signals are positive-edge triggered.

A 32-bit counter can be realized by connecting CLKA and CLKB together and by connecting RCOA to CLKBEN.

To ensure the high-impedance state during power up or power down, GAL, GAU, GBL, and GBU should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

TA	PACKA	AGET	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74LV8154N	SN74LV8154N
–40°C to 85°C	10°C to 85°C		SN74LV8154PW	11/0454
	1350P - PW	Tape and reel	SN74LV8154PWR	LV8154

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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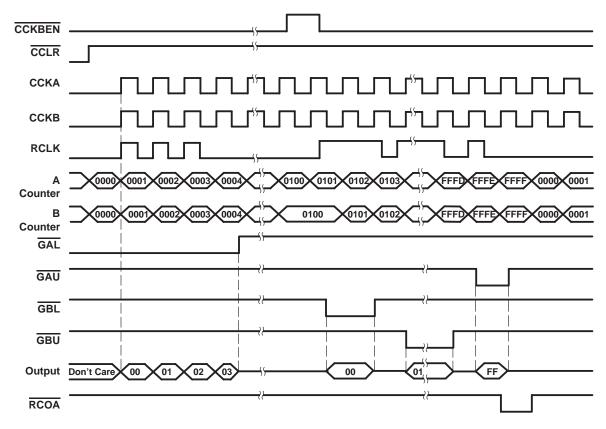
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FUNCTION TABLE (each buffer)

	INP	UTS		OUTPUT
GAL	GAU	GBL	GBU	Yn
L	Н	Н	Н	Lower byte in A register
н	L	Н	Н	Upper byte in A register
Н	Н	L	Н	Lower byte in B register
Н	Н	Н	L	Upper byte in B register
Н	Н	Н	Н	Z

Combinations of GAL, GAU, GBL, GBU, other than those shown above, are prohibited. If more than one input is L at the same time, the output data (Y0-Y7) may . be invalid.

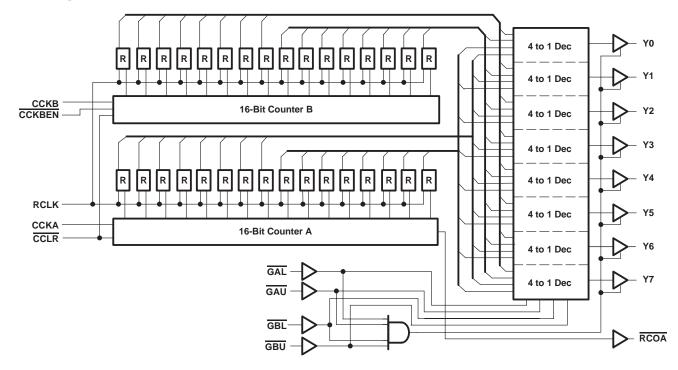
timing diagram





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block diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} Input voltage range, V_I (see Note 1)	
Voltage range applied to any output in the high-impedance	
or power-off state, V _O (see Note 1)	–0.5 V to 7 V
Output voltage range, V _O (see Notes 1 and 2)	0.5 V to V _{CC} + 0.5 V
Input clamp current, I _{IK} (V _I < 0)	–20 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, I_{O} (V _O = 0 to V _{CC})	±35 mA
Continuous current through V _{CC} or GND	
Package thermal impedance, θ_{JA} (see Note 3): N package	
PW package	
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. This value is limited to 5.5 V maximum.

3. The package thermal impedance is calculated in accordance with JESD 51-7.



SN74LV8154 DUAL 16-BIT BINARY COUNTERS WITH 3-STATE OUTPUT REGISTERS SCLS589 - AUGUST 2004

recommended operating conditions (see Note 4)

			VCC	MIN	MAX	UNIT
VCC	Supply voltage			2	5.5	V
			2 V	1.5		
VIH	High-level input voltage		3 V to 3.6 V	$V_{CC} \times 0.7$		V
			4.5 V to 5.5 V	$V_{CC} \times 0.7$		
			2 V		0.5	
VIL	Low-level input voltage		3 V to 3.6 V		$V_{CC} \times 0.3$	V
			4.5 V to 5.5 V		$V_{CC} \times 0.3$	
VI	Input voltage			0	5.5	V
		High or low state		0	VCC	
VO	Output voltage	3-state		0	5.5	V
			2 V		-50	μA
		Yn outputs	3 V to 3.6 V		-6	
	High-level output current		4.5 V to 5.5 V		-12	mA
ЮН			2 V		-50	μA
		RCOA	3 V to 3.6 V		-6	
			4.5 V to 5.5 V		-12	mA
			2 V		50	μA
		Yn outputs	3 V to 3.6 V		6	
			4.5 V to 5.5 V		12	mA
IOL	Low-level output current		2 V		50	μA
		RCOA	3 V to 3.6 V		6	
					12	mA
/ .			3 V to 3.6 V		100	
$\Delta t / \Delta v$	Input transition rise or fall rate		4.5 V to 5.5 V		20	ns/∖
TA	Operating free-air temperature			-40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SN74LV8154 **DUAL 16-BIT BINARY COUNTERS** WITH 3-STATE OUTPUT REGISTERS SCLS589 - AUGUST 2004

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMET	ER	TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
		I _{OH} = -50 μA	2 V	1.9			
	Yn	$I_{OH} = -6 \text{ mA}$	3 V	2.48			
		$I_{OH} = -12 \text{ mA}$	4.5 V	3.8			V
VOH		I _{OH} = -50 μA	2 V	1.9			V
	RCOA	$I_{OH} = -6 \text{ mA}$	3 V	2.48			
		$I_{OH} = -12 \text{ mA}$	4.5 V	3.8			
		I _{OL} = 50 μA	2 V			0.1	
	Yn	$I_{OL} = 6 \text{ mA}$	3 V			0.44	
		I _{OL} = 12 mA	4.5 V			0.55	
VOL		I _{OL} = 50 μA	2 V			0.1	V
	RCOA	I _{OL} = 6 mA	3 V			0.44	
		I _{OL} = 12 mA	4.5 V			0.55	
lj		$V_{I} = 5.5 \text{ V or GND}$	0 to 5.5 V			±1	μΑ
I _{OZ}		$V_{O} = V_{CC}$ or GND	5.5 V			±5	μΑ
Icc		$V_{I} = V_{CC}$ or GND, $I_{O} = 0$	5.5 V			20	μΑ
l _{off}		V_{I} or $V_{O} = 0$ to 5.5 V	0			5	μΑ
Ci		$V_{I} = V_{CC}$ or GND	5 V		3		pF
Co		$V_{O} = V_{CC}$ or GND	5 V		5		pF

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

			MIN	MAX	UNIT
	Dulas duration	CLKA, CLKB, RCLK high or low	10		~~~
tw	Pulse duration	CCLR low	22		ns
		CLKBEN low before CLKB [↑]	13		
		CCLR high (inactive) before CLKA↑ or CLKB↑	13		
t	Setup time	CLKA↑ or CLKB↑ before RCLK↑	13		ns
t _{su}	Setup time	RCLK [↑] before GAL or GAU or GBL or GBU low			115
		GAL or GAU or GBL or GBU high (inactive) before RCLK↑	13		
		CLKBEN low after CLKB [↑]	0		
th	Hold time	CLKA or CLKB after RCLK	0		ns
tz†	Z-period	GAL, GAU, GBL, GBU all high before one of them switches low	200		ns

† t_z condition: C_L = 50 pF, R_L = 1 kΩ



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timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

			MIN	MAX	UNIT	
	Deduce down from	CLKA, CLKB, RCLK high or low	10			
tw	Pulse duration	CCLR low	20		ns	
		CLKBEN low before CLKB [↑]	10			
		CCLR high (inactive) before CLKA↑ or CLKB↑	10			
+	Setup time	CLKA↑ or CLKB↑ before RCLK↑				
t _{su}		RCLK [↑] before GAL or GAU or GBL or GBU low	10		ns	
		GAL or GAU or GBL or GBU high (inactive) before RCLK↑	10			
4.		CLKBEN low after CLKB [↑]	0			
th	Hold time	CLKA or CLKB after RCLK	0		ns	
tz†	Z-period	GAL, GAU, GBL, GBU all high before one of them switches low	200		ns	

 t_z condition: C_L = 50 pF, R_L = 1 kΩ

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

	FROM	то	LOAD	Тд	(= 25°C	;			
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
farax			C _L = 15 pF				40		N 41 1-
fMAX			$C_L = 50 \text{ pF}$				25		MHz
÷ .	RCLK	Y			22		1	38	
^t pd	CLKA	RCOA]		26		1	44	ns
^t PLH	CCLR	RCOA	CL = 15 pF		18		1	32	ns
ten	GAL, GAU, GBL, GBU	Y			27		1	46	ns
^t dis	GAL, GAU, GBL, GBU	Y			12		1	21	ns
	RCLK	Y			25		1	42	
tpd	CLKA	RCOA			28		1	46	ns
^t PLH	CCLR	RCOA	С _L = 50 рF		20		1	35	ns
ten	GAL, GAU, GBL, GBU	Y			30		1	50	ns
^t dis	GAL, GAU, GBL, GBU	Y			14		1	24	ns



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switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

	FROM	то	LOAD	Τį	₄ = 25°C	;			
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
f1 1 1 1			CL = 15 pF				40		N 41 1-
fMAX			C _L = 50 pF				25		MHz
+ .	RCLK	Y			14		1	25	
^t pd	CLKA	RCOA			16		1	27	ns
^t PLH	CCLR	RCOA	C _I = 15 pF		12		1	20	ns
ten	GAL, GAU, GBL, GBU	Y			16		1	28	ns
^t dis	GAL, GAU, GBL, GBU	Y	7		8		1	15	ns
4 .	RCLK	Y			16		1	27	
^t pd	CLKA	RCOA			17		1	28	ns
^t PLH	CCLR	RCOA	C _L = 50 pF		13		1	21	ns
t _{en}	GAL, GAU, GBL, GBU	Y			18		1	30	ns
^t dis	GAL, GAU, GBL, GBU	Y			9		1	16	ns

noise characteristics, V_{CC} = 5 V, C_L = 50 pF

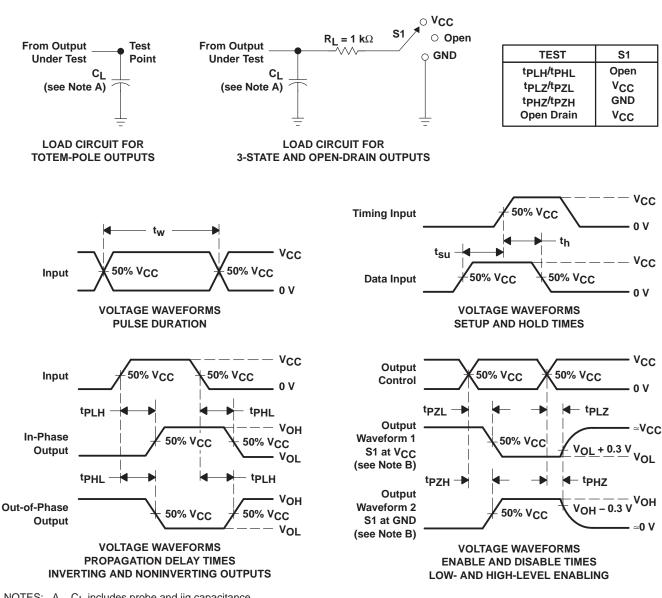
	PARAMETER		T _A = 25°C		
	PARAMETER	MIN			UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.7		V
VOL(V)	Quiet output, minimum dynamic V _{OL}		-0.75		V
VOH(V)	Quiet output, minimum dynamic V _{OH}		4.4		V

operating characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER		TEST CONDITIONS			UNIT
Cpd	Power dissipation capacitance	$C_L = No load,$	CCLK = 10 MHz,	RCLK = 1 MHz	56	pF



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control. C. All input pulses are supplied by generators having the following characteristics: $PRR \le 1$ MHz, $Z_O = 50 \Omega$, $t_f \le 3$ ns, $t_f \le 3$ ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. tPLZ and tPHZ are the same as tdis.
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. tPHL and tPLH are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LV8154N	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LV8154NE4	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LV8154PW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV8154PWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV8154PWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV8154PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV8154PWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV8154PWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74LV8154 :

Enhanced Product: SN74LV8154-EP

NOTE: Qualified Version Definitions:





18-Sep-2008

• Enhanced Product - Supports Defense, Aerospace and Medical Applications

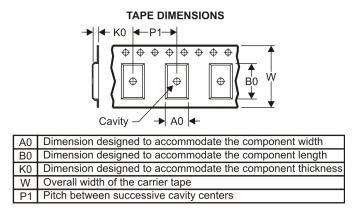
PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV8154PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

5-May-2011



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV8154PWR	TSSOP	PW	20	2000	346.0	346.0	33.0

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES:

A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994. β . This drawing is subject to change without notice.

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153



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